

Title (en)
IRON-NICKEL ALLOY STRIP FOR THE MANUFACTURE OF SUPPORT GRIDS FOR INTEGRATED CIRCUITS

Title (de)
EISEN-NICKEL-LEGIERUNGSSTREIFEN ZUR HERSTELLUNG VON HALTEGITTERN FÜR INTEGRIERTE SCHALTKREISE

Title (fr)
BANDE D ALLIAGE FER-NICKEL POUR LA FABRICATION DE GRILLES SUPPORT DE CIRCUITS INTEGRES

Publication
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Application
EP 05814999 A 20051104

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Abstract (en)
[origin: WO2006051188A2] The invention concerns an iron-nickel alloy strip comprising the following expressed in wt. %: 32 = Co + Ni = 45 %, 0 = Co = 6.5 %, 0 = Cr = 6.5 %, Cu = 3 %, Si = 0.5 %, Mn = 0.75 %, the rest being made up of iron and unavoidable impurities resulting from production, whereof the microstructure has a recrystallized volume fraction ranging from 3 to 97 %, whereof the thickness is less than 0.5 mm. The invention also concerns the use thereof in the manufacture of support grids for integrated circuits.

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